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SHEET 1 OF 26

INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION

(PTO-1449)

ATTY. DOCKET NO.
7720/FPS/MMCS/APC

SERIAL NO.
10/632,107

APPLICANT
Alexander T. SCHWARM et al.

FILING DATE
August 1, 2003

GROUP
2812

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,497,381	03/05/96	O'Donoghue et al.			06/01/95
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	6,161,054 B1	12/12/00	Rosenthal et al.			09/17/98
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	6,368,884 B1	04/09/02	Goodwin et al.			04/13/00
	6,405,096 B1	06/11/02	Toprac et al.			08/10/99
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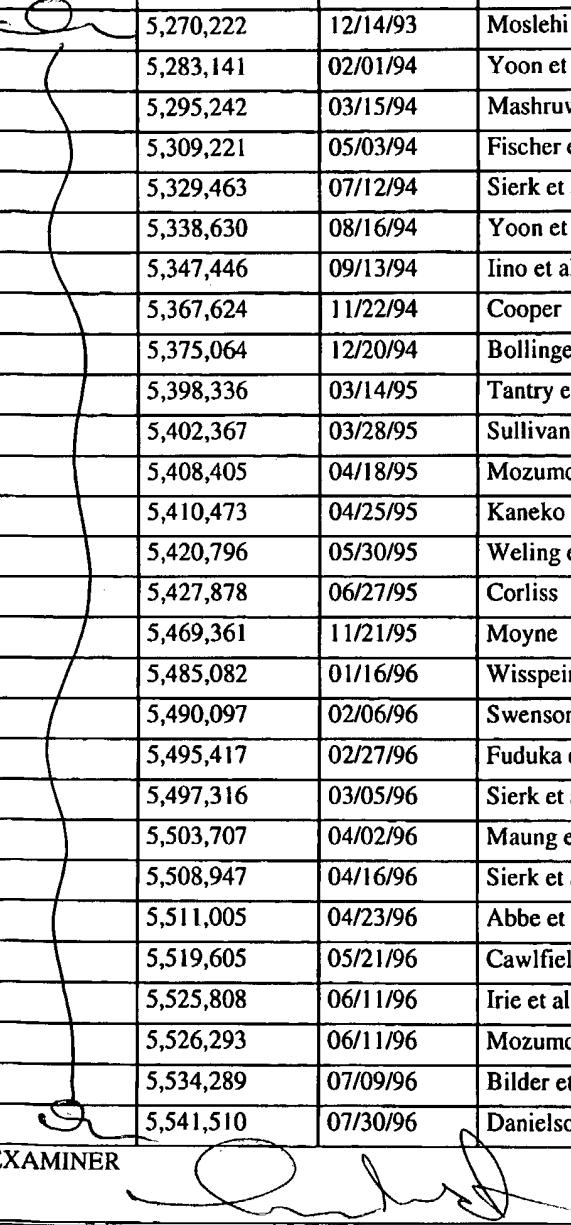
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	Yeh, C. Eugene, John C. Cheng, and Kwan Wong. 1993. "Implementation Challenges of a Feedback Control System for Wafer Fabrication." <i>IEEE/CHMT International Electronics Manufacturing Technology Symposium</i> , pp. 438-442.
	Fan, Jr-Min, Ruey-Shan Guo, Shi-Chung Chang, and Kian-Huei Lee. 1996. "Abnormal Trend Detection of Sequence-Disordered Data Using EWMA Method." <i>IEEE/SEMI Advanced Semiconductor Manufacturing Conference</i> , pp. 169-174.
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	Guo, Ruey-Shan, Li-Shia Huang, Argon Chen, and Jin-Jung Chen. October 1997. "A Cost-Effective Methodology for a Run-by-Run EWMA Controller." <i>6th International Symposium on Semiconductor Manufacturing</i> , pp. 61-64.
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	Chen, Argon and Ruey-Shan Guo. February 2001. "Age-Based Double EWMA Controller and Its Application to CMP Processes." <i>IEEE Transactions on Semiconductor Manufacturing</i> , vol. 14, no. 1, pp. 11-19.
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	December 16, 2003. International Search Report for PCT/US03/23964.
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	3,229,198	01/11/66	Libby			09/28/62
	3,767,900	10/23/73	Chao et al.			06/23/71
	3,920,965	11/18/75	Sohrwardy			03/04/74
	4,000,458	12/28/76	Miller et al.			08/21/75
	4,207,520	06/10/80	Flora et al.			04/06/78
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	4,302,721	11/24/81	Urbanek et al.			05/15/79
	4,368,510	01/11/83	Anderson			10/20/80
	4,609,870	09/02/86	Lale et al.			09/13/84
	4,616,308	10/07/86	Morshedi et al.			12/02/85
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	4,698,766	10/06/87	Entwistle et al.			05/17/85
	4,750,141	06/07/88	Judell et al.			11/26/85
	4,755,753	07/05/88	Chern			07/23/86
	4,757,259	07/12/88	Charpentier			11/05/86
	4,796,194	01/03/89	Atherton			08/20/86
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	5,208,765	05/04/93	Turnbull			07/20/90
	5,220,517	06/15/93	Sierk et al.			08/31/90
	5,226,118	07/06/93	Baker et al.			01/29/91
	5,231,585	07/27/93	Kobayashi et al.			06/20/90
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U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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	5,283,141	02/01/94	Yoon et al.			03/05/92
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	5,402,367	03/28/95	Sullivan et al.			07/19/93
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	5,735,055	04/07/98	Hochbein et al.			04/23/96
	5,740,429	04/14/98	Wang et al.			07/07/95
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
<i>SL</i>	5,751,582	05/12/98	Saxena et al.			09/24/96
	5,754,297	05/19/98	Nulman			04/14/97
	5,761,064	06/02/98	La et al.			10/06/95
	5,764,543	06/09/98	Kennedy			06/16/95
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	5,912,678	06/15/99	Saxena et al.			04/14/97
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
<i>ec</i>	6,127,263	10/03/00	Parikh			07/10/98
<i>ec</i>	6,128,016	10/03/00	Coelho et al.			12/20/96
<i>ec</i>	6,136,163	10/24/00	Cheung et al.			03/05/99
	6,141,660	10/31/00	Bach et al.			07/16/98
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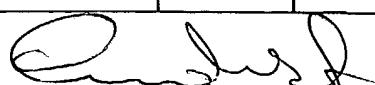
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	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
	09/637,620	08/11/00	Chi et al.	Generic Interface Builder			
	09/656,031	09/06/00	Chi et al.	Dispatching Component for Associating Manufacturing Facility Service Requestors with Service Providers			
	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
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	09/800,980	03/08/01	Hawkins et al.	Dynamic and Extensible Task Guide			
	09/811,667	03/20/01	Yuan et al.	Fault Tolerant and Automated Computer Software Workflow			
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	09/943,383	08/31/01	Shanmugasundram et al.	In Situ Sensor Based Control of Semiconductor Processing Procedure			
	09/943,955	08/31/01	Shanmugasundram et al.	Feedback Control of a Chemical Mechanical Polishing Device Providing Manipulation of Removal Rate Profiles			
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	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements			
	10/135,405	05/01/02	Reiss et al.	Integration of Fault Detection with Run-to-Run Control			
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	10/172,977	06/18/02	Shanmugasundram et al.	Method, System and Medium for Process Control for the Matching of Tools, Chambers and/or Other Semiconductor-Related Entities			
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	10/174,370	06/18/02	Shanmugasundram et al.	Feedback Control of Plasma-Enhanced Chemical Vapor Deposition Processes			
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	10/371,654	03/04/03	Kokotov et al.	Method, System and Medium for Controlling Manufacturing Process Using Adaptive Models Based on Empirical Data			
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						Yes	No
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	61-171147	08/01/86	Japan			X	
	01-283934	11/15/89	Japan			X	
	0 397 924 A1	11/22/90	Europe			X	
	2,050,247	08/29/91	Canada			X	
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	3-202710	09/04/91	Japan			X	
	05-151231	06/18/93	Japan			X	
	05-216896	08/27/93	Japan			X	
	05-266029	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
	06-184434	07/05/94	Japan			X	
	06-252236	09/09/94	Japan			X	
	06-260380	09/16/94	Japan			X	
	EP 0 621 522 A2	10/26/94	Europe			X	
	WO 95/34866	12/21/95	WO			X	
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EXAMINER		DATE CONSIDERED	

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.